

**ASSIGNMENT
UNITED STATES OF AMERICA**

Whereas, I/We (1) RICHARD F. HILL

AND FOREST HAMPTON III

of (2) 17335 Nash Rd, Parkman, OH 44080

and 449 Kenyon Ave. , Elyria, OH 44035

MULTI-LAYER STRUCTURE AND
have invented certain new and useful improvements in (3) METHOD FOR FORMING A THERMAL
INTERFACE WITH LOW CONTACT RESISTANCE BETWEEN A MICROELECTRONIC COMPONENT
PACKAGE AND HEAT SINK

for which application for Letters Patent in the United States of America (4) a) is about to be
made or b) has been made;

And Whereas, (5) THERMAGON, INC.

of (6) 3256 West 25th Street, Cleveland Ohio 44102

is/are desirous of acquiring an interest therein and in the Letters Patent to be obtained
therefor;

Now Therefore, be it known by all whom it may concern, that for good and valuable
consideration (the sufficiency of which is hereby acknowledged) I/we have assigned,
transferred and set over, and by these presents do assign, transfer and set over unto the said
(5) THERMAGON, INC.

territory of the United States of America, and not elsewhere; the full and exclusive right, title,
and interest in and to the said invention, as fully set forth and described in the specification

(7) prepared and executed by me/us on (8) Feb. 24, 2000

or filed in the U.S. Patent Office under Ser. No. (9) _____ on (10) _____

preparatory to obtaining Letters Patent therefor; said invention, application and Letters Patent to be held and enjoyed by the said (5) THERMAGON, INC.

_____ to the full end of the term for which said Letters Patent are granted, as fully and entirely as the same would have been held by me/us had this assignment and transfer not been made.

In testimony whereof, I/we have hereunto set my/our hand this

(11) 24 day of FEBRUARY 2000

WITNESSES:

Katherine Chubart

Edna F. Susko

INVENTOR(S):

(1) Richard F. Hill

(2) Forest Hampton III

(3) _____

(4) _____